



A1N:100.XXH

VOLTAGE RATINGS

Part Number	V_{RRM} , V_R (V)		V_{RSM} , V_R (V) Max. non-rep. peak reverse voltage
	$T_J = 0$ to 125°C	$T_J = -40$ to 0°C	
A1N:100.02H	200	200	300
A1N:100.04H	400	400	500
A1N:100.06H	600	600	700
A1N:100.08H	800	800	900
A1N:100.10H	1000	1000	1100
A1N:100.12H	1200	1200	1300
A1N:100.14H	1400	1330	1500
A1N:100.16H	1600	1520	1700

This datasheet applies to:

Metric thread: A1N:100.XXH

Inch thread: A2N:100.XXH

MAXIMUM ALLOWABLE RATINGS

PARAMETER	VALUE	UNITS	NOTES
T_J Junction Temperature	-40 to 125	$^\circ\text{C}$	-
T_{stg} Storage Temperature	-40 to 150	$^\circ\text{C}$	-
$I_{T(AV)}$	Max. Av. current	A	180° half sine wave
	@ Max. T_C	$^\circ\text{C}$	
$I_{T(RMS)}$ Nom. RMS current	175	A	-
I_{TSM} Max. Peak non-rep. surge current	1.80	kA	50 Hz half cycle sine wave
	1.96		60 Hz half cycle sine wave
	2.07		50 Hz half cycle sine wave
	2.26		60 Hz half cycle sine wave
I^2t Max. I^2t capability	21.45	kA ² s	$t = 10\text{ms}$
	23.38		$t = 8.3 \text{ ms}$
	30.28		$t = 10\text{ms}$
	33.00		$t = 8.3 \text{ ms}$
$I^{2t^{1/2}}$ Max. $I^{2t^{1/2}}$ capability	360	kA ² s ^{1/2}	Initial $T_J = 125^\circ\text{C}$, no voltage applied after surge. I^2t for time $t_x = I^{2t^{1/2}} * t_x^{1/2}$. ($0.1 < t_x < 10\text{ms}$).
di/dt Max. Non-repetitive rate-of-rise current	800	A/ s	$T_J = 125^\circ\text{C}$, $V_D = V_{DRM}$. $I_{TM} = 1600\text{A}$. Gate pulse: 20V, 20 , 10 s, 0.5 s rise time, Max. repetitive di/dt is approximately 40% of non-repetitive value.
$P_G M$ Max. Peak gate power	10	W	$tp < 5 \text{ ms}$
$P_{G(AV)}$ Max. Av. gate power	2	W	-
+ I_{GM} Max. Peak gate current	150	mA	$tp < 5 \text{ ms}$
- V_{GM} Max. Peak negative gate voltage	2	V	-
F Mounting Force	16	N.m	Non lubricated threads



A1N:100.XXH

CHARACTERISTICS

PARAMETER	MIN.	TYP.	MAX.	UNITS	TEST CONDITIONS
V_{TM} peak on-state voltage	---	---	1.58	V	Initial $T_J = 25^\circ C$, 50-60Hz half sine, $I_{peak} = 188A$.
$V_{T(TO)}$ Threshold voltage	---	---	0.8	V	$T_J = 125^\circ C$ Av. power = $V_{T(TO)} * I_{T(AV)} + r_T * [I_{T(RMS)}]^2$, 180° Half Sine.
r_T Slope resistance	---	---	1.182	m	Use low values for $I_{TM} <$ rated $I_{T(AV)}$
I_L Latching current	---	---	400	mA	$T_C = 125^\circ C$, 12V anode. Gate pulse: 10V, 20 , 100 s.
I_H Holding current	---	---	200	mA	$T_C = 25^\circ C$, 12V anode. Initial $I_T = 15A$.
t_d Delay time	---	0.7	1	s	$T_C = 25^\circ C$, $V_D = V_{DRM}$, 50A resistive load. Gate pulse: 10V, 20 , 10 s, 1 s rise time.
t_q Turn-off time	---	---	110	s	$T_J = 125^\circ C$, $I_{TM} = 500A$, $di/dt = 25A/ s$, $V_R = 50V$. $dv/dt = 20V/ s$ lin. to rated V_{DRM} . Gate: 0V, 100 .
dv/dt Critical rate-of-rise of off-state voltage	---	---	1000	V/ s	$T_J = 125^\circ C$, Exp. To 67% V_{DRM} , gate open.
I_{RM} , I_{DM} Peak reverse and off-state current	---	10	20	mA	$T_J = 125^\circ C$, Rated V_{RRM} and V_{DRM} , gate open.
I_{GT} DC gate current to trigger	---	---	300	mA	$T_C = -40^\circ C$
	50	80	150	mA	$T_C = 25^\circ C$ +12V anode-to-cathode. For recommended
V_{GT} DC gate voltage to trigger	5	---	---	V	$T_C = -40^\circ C$ gate drive see "Gate Characteristics" figure.
	2.5	---	---	V	$T_C = 25^\circ C$
V_{GD} DC gate voltage not to trigger	---	---	0.3	V	$T_C = 25^\circ C$, Max. Value which will not trigger with rated V_{DRM} anode.
R_{thJC} Thermal resistance, junction-to-case	---	---	0.25	°C/W	DC operation, single side coolde.
	---	---	0.295	°C/W	180° sine wave, single side coolde.
	---	---	0.36	°C/W	120° rectangular wave, single side cooled.
R_{thCS} Thermal resistance, case-to-sink	---	---	0.1	°C/W	Mtg. Surface smooth, flat and greased. Single side cooled.
wt Weight	---	130(4.8)	---	g(oz.)	---
Case Style	TO-209AC(TO-94)		JEDEC		---

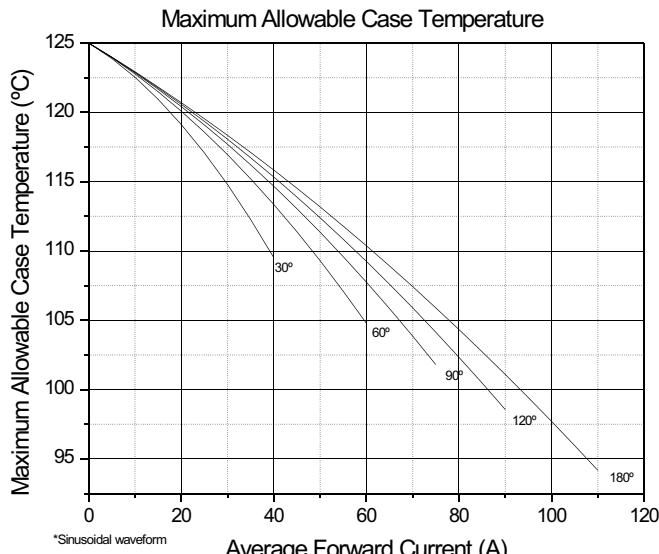


Fig. 1 - Current Ratings Characteristics

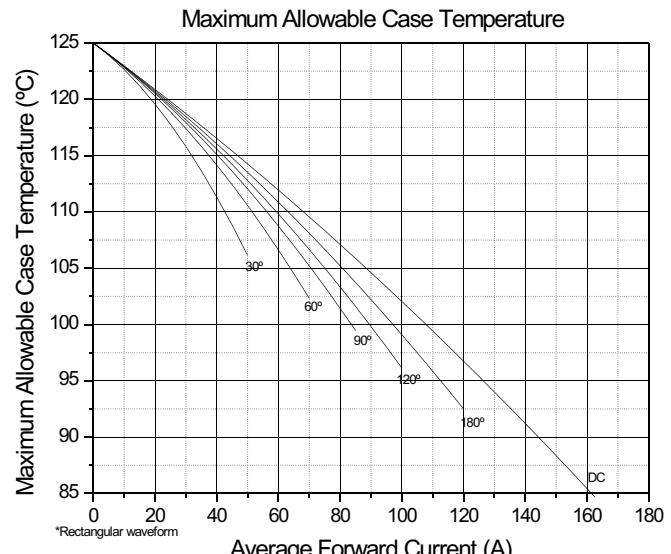


Fig. 2 - Current Ratings Characteristics



A1N:100.XXH

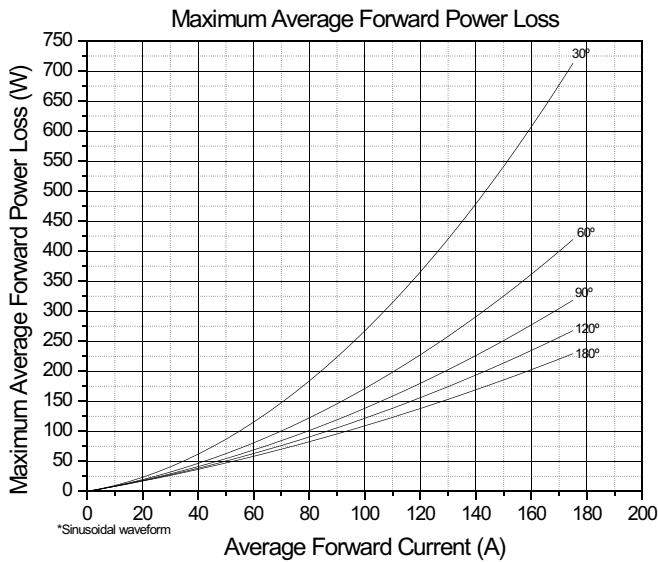


Fig. 3 - Forward Power Loss Characteristics

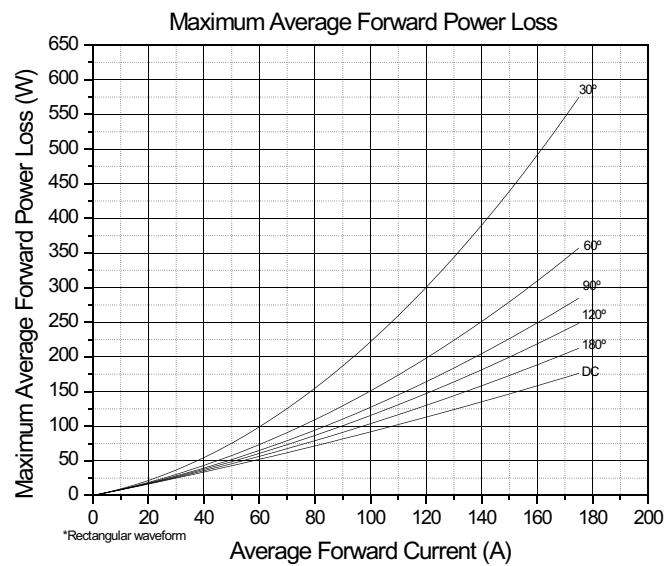


Fig. 4 - Forward Power Loss Characteristics

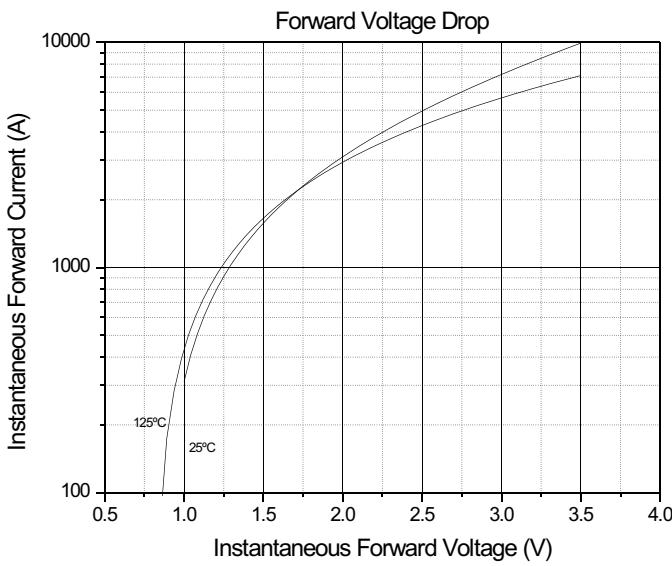


Fig. 5 - Forward Voltage Drop Characteristics

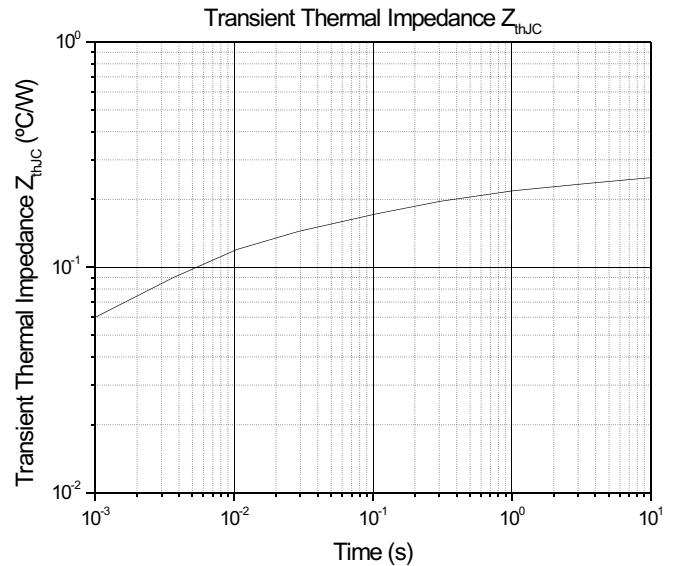


Fig. 6 - Transient Thermal Impedance Characteristics



AEGIS
SEMICONDUTORES LTDA.

A1N:100.XXH

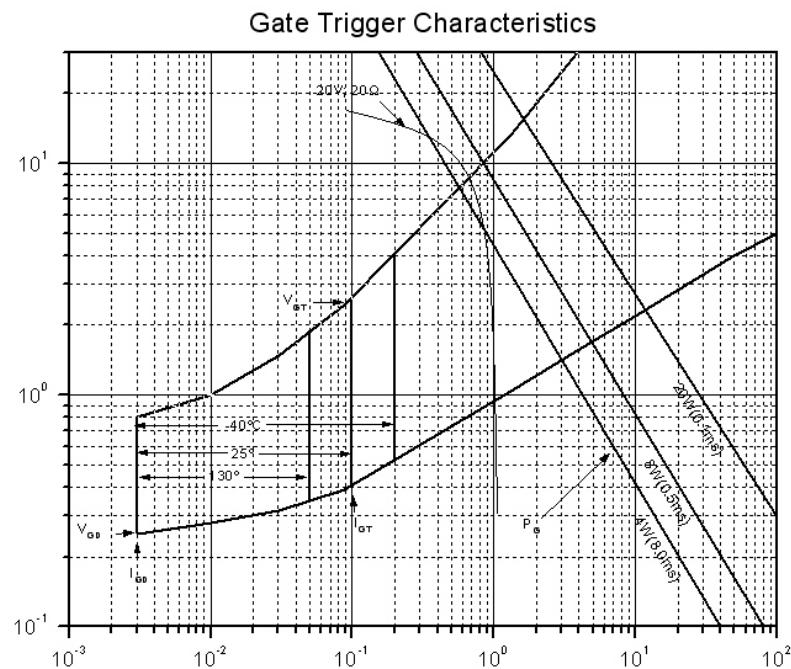


Fig. 7 - Gate Trigger Characteristics

TO-209AC (TO-94)

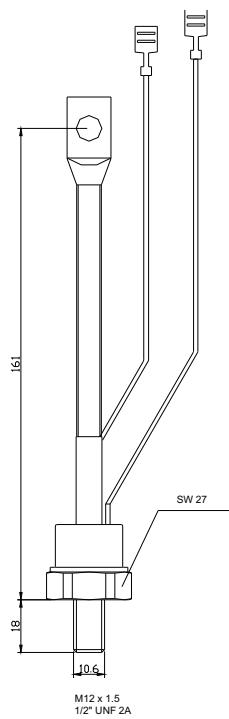


Fig. 8 - Outline Characteristics